

300-MHz, 2.5-Ω, Dual SPDT Analog Switches

DESCRIPTION

The DG3516/DG3517 are dual SPDT analog switches which operate from 1.8 V to 5.5 V single rail power supply. They are design for audio, video, and USB switching applications.

The devices have 2.5 Ω on-resistance and 300 MHz 3dB bandwidth. 0.2 Ω on-resistance matching and 1 Ω flatness make the device high linearity. The devices are 1.6 V logic compatible within the full operation voltage range.

These switches are built on a sub-micron high density process that brings low power consumption and low voltage performance.

The switches are packaged in MICRO FOOT chip scale package of 4 x 3 bump array.

As a committed partner to the community and environment, Vishay Siliconix manufactures this product with the lead (Pb)-free device terminations. For MICRO FOOT analog switch products manufactured with tin/silver/copper (SnAgCu) device termination, the lead (Pb)-free "-E1" suffix is being used as a designator.

FEATURES

- 1.8 V to 5.5 V Operation
- 2.5 Ω at 2.7 V r_{ON}
- 300 MHz - 3 dB Bandwidth
- ESD Method 3015.7 > 2 kV
- Latch-Up Current 200 mA (JESD 78)
- 1.6 V Logic Compatible


RoHS
COMPLIANT

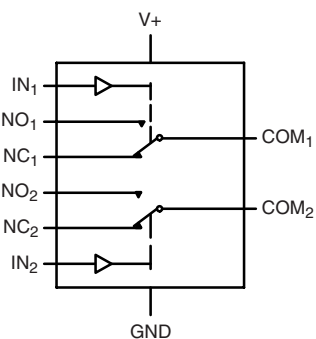
BENEFITS

- Space Saving MICRO FOOT® Package
- High Linearity
- Low Power Consumption
- High Bandwidth
- Full Rail Signal Swing Range

APPLICATIONS

- Cellular Phones
- MP3
- Media Players
- Modems
- Hard Drives
- PCMCIA

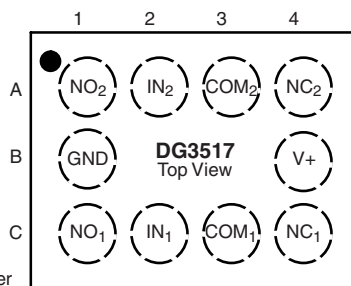
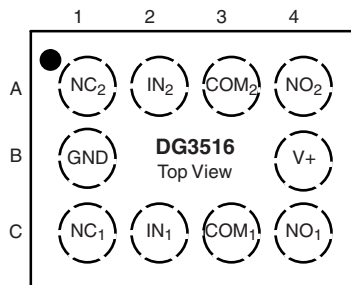
FUNCTIONAL BLOCK DIAGRAM AND PIN CONFIGURATION

DG3516/DG3517
MICRO FOOT 10-Bump

Device Marking

A1 Locator



3516 = Example Base Part Number
xxx = Data/Lot Traceability Code



TRUTH TABLE

Logic	NC1 and NC2	NO1 and NO2
0	ON	OFF
1	OFF	ON

ORDERING INFORMATION

Temp Range	Package	Part Number
- 40 to 85 °C	MICRO FOOT: 10 Bump (4 x 3, 0.5 mm Pitch, 238 μm Bump Height)	DG3516DB-T5-E1 DG3517DB-T5-E1

ABSOLUTE MAXIMUM RATINGS			
Parameter		Limit	Unit
Reference V+ to GND		- 0.3 to + 6	V
IN, COM, NC, NO ^a		- 0.3 to (V+ + 0.3 V)	
Continuous Current (NO, NC, COM)		± 100	mA
Peak Current (Pulsed at 1 ms, 10 % duty cycle)		± 200	
Storage Temperature	(D Suffix)	- 65 to 150	°C
Package Solder Reflow Conditions ^b	IR/Convection	250	
ESD per Method 3015.7		> 2	kV
Power Dissipation (Packages) ^c	MICRO FOOT: 10 Bump (4 x 3 mm) ^d	457	mW

Notes:

- a. Signals on NC, NO, or COM or IN exceeding V+ will be clamped by internal diodes. Limit forward diode current to maximum current ratings.
- b. Refer to IPC/JEDEC (J-STD-020B)
- c. All bumps welded or soldered to PC Board.
- d. Derate 5.7 mW/°C above 70 °C.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

SPECIFICATIONS (V+ = 3 V)								
Parameter	Symbol	Test Conditions Otherwise Unless Specified V+ = 2.7 to 3.6 V, V _{IN} = 0.5 V or 1.4 V ^e	Temp ^a	Limits - 40 to 85 °C			Unit	
				Min ^b	Typ ^c	Max ^b		
Analog Switch								
Analog Signal Range ^d	V _{NO} , V _{NC} , V _{COM}		Full	0		V+	V	
On-Resistance ^d	r _{ON}	V+ = 2.7 V I _{NO} , I _{NC} = 10 mA	Room Full		2.5	3.5 3.8	Ω	
r _{ON} Flatness ^d	r _{ON} Flatness		V _{COM} = 1, 1.5, 2 V	Room		0.52		1.0
On-Resistance Match Between Channels ^d	Δr _{DS(on)}		V _{COM} = 1.5 V	Room				0.25
Switch Off Leakage Current	I _{NO(off)} I _{NC(off)}	V+ = 3.3 V, V _{NO} , V _{NC} = 0.3 V/3 V, V _{COM} = 3 V/0.3 V	Room Full	- 2 - 20		2 20	nA	
	I _{COM(off)}		Room Full	- 2 - 20		2 20		
Channel-On Leakage Current	I _{COM(on)}	V+ = 3.3 V, V _{NO} , V _{NC} = V _{COM} = 0.3 V/3 V	Room Full	- 2 - 20		2 20		
Digital Control								
Input High Voltage ^d	V _{INH}		Full	1.4			V	
Input Low Voltage	V _{INL}		Full			0.5		
Input Capacitance	C _{in}		Full		5		pF	
Input Current	I _{INL} or I _{INH}	V _{IN} = 0 or V+	Full	1		1	μA	

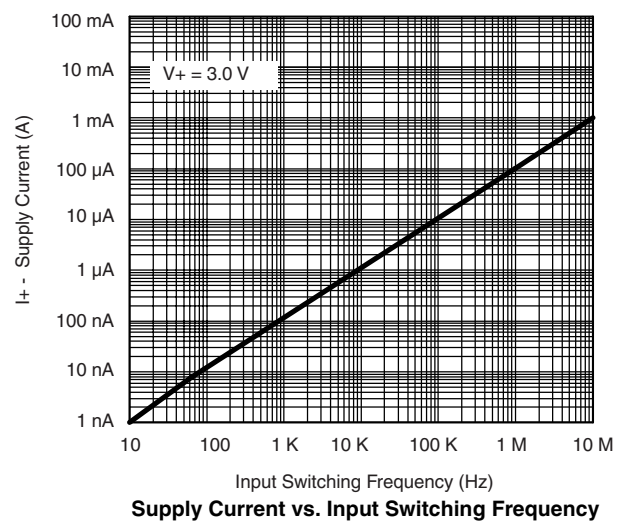
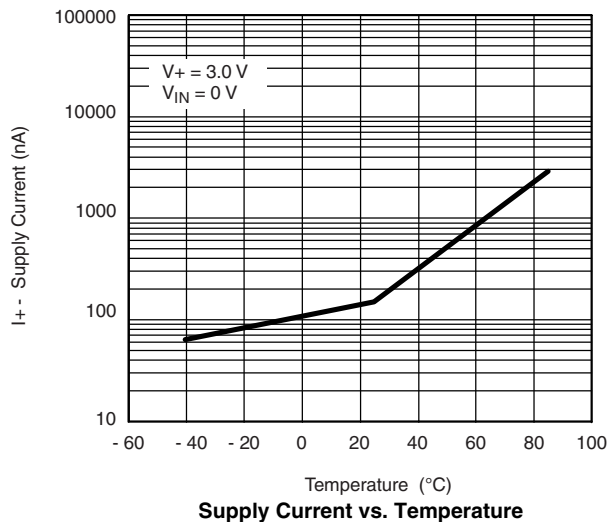
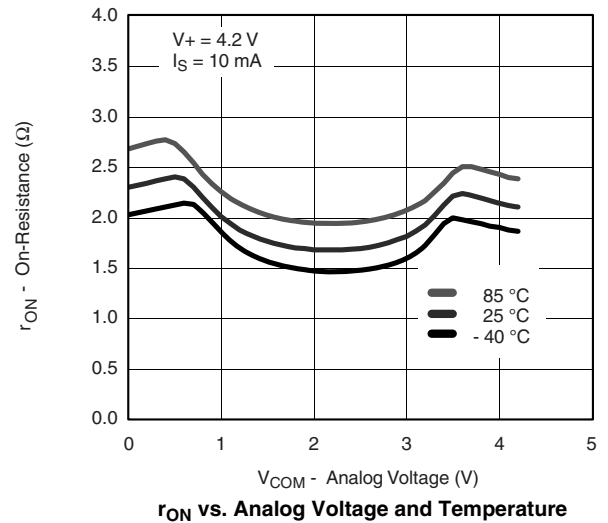
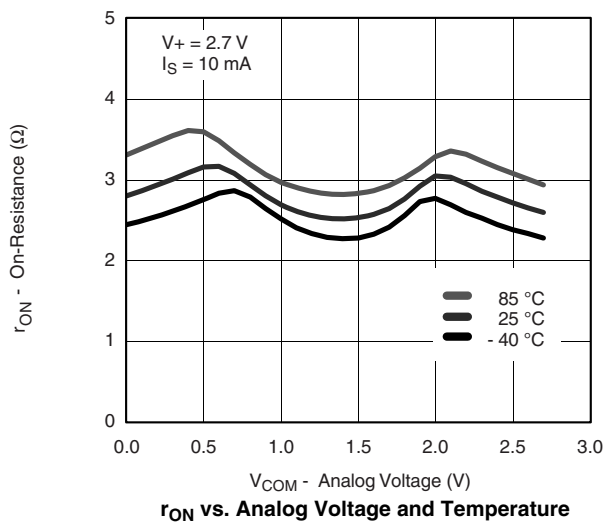
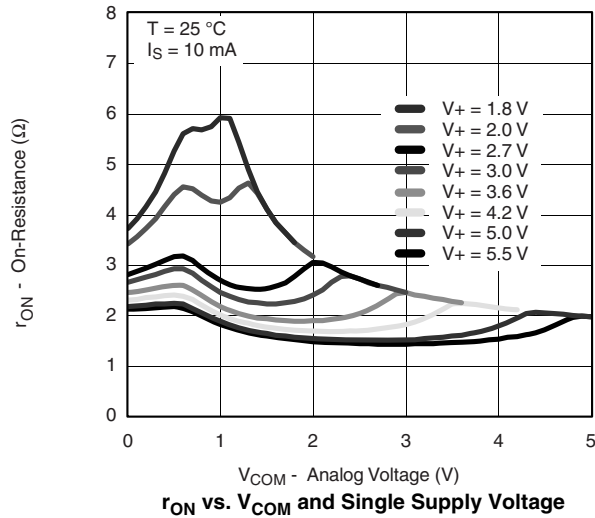


SPECIFICATIONS (V+ = 3 V)									
Parameter	Symbol	Test Conditions Otherwise Unless Specified V+ = 2.7 to 3.6 V, VIN = 0.5 V or 1.4 V ^e	Temp ^a	Limits - 40 to 85 °C			Unit		
				Min ^b	Typ ^c	Max ^b			
Dynamic Characteristics									
Turn-On Time	t _{ON}	V+ = 2.7 V, V _{NO} or V _{NC} = 1.5 V R _L = 300 Ω, C _L = 35 pF	Room Full		21	51	ns		
Turn-Off Time	t _{OFF}		Room Full		15	45			
Break-Before-Make Time	t _d		Full	1		46			
Charge Injection ^d	Q _{INJ}	C _L = 1 nF, V _{GEN} = 2.0 V, R _{GEN} = 0 Ω	Room		1		pC		
Off-Isolation ^d	OIRR	R _L = 50 Ω, C _L = 5 pF	f = 1 MHz	Room	- 74		dB		
			f = 10 MHz	Room	- 54				
Crosstalk ^d	X _{TALK}		f = 1 MHz	Room	- 76				
			f = 10 MHz	Room	- 56				
N _O , N _C Off Capacitance ^d	C _{NO(off)}	V _{IN} = 0 or V+, f = 1 MHz	Room		12		pF		
	C _{NC(off)}		Room		12				
Channel-On Capacitance ^d	C _{NO(on)}		Room		40				
	C _{NC(on)}		Room		40				
Power Supply									
Power Supply Current	I+		V _{IN} = 0 or V+	Room Full				1.0 1.0	μA

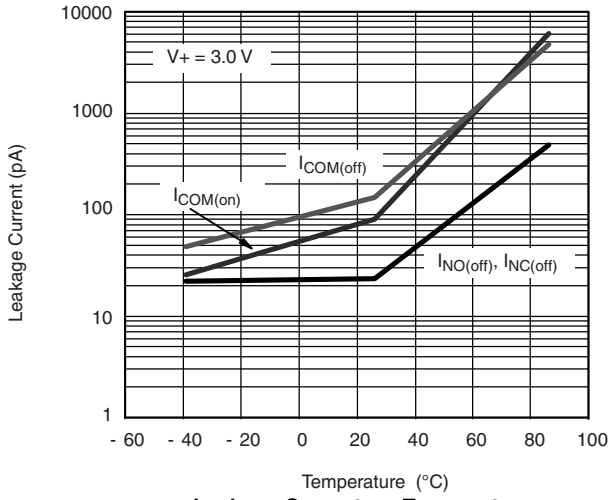
SPECIFICATIONS (V+ = 5 V)									
Parameter	Symbol	Test Conditions Otherwise Unless Specified V+ = 4.2 to 5.5 V, VIN = 0.8 V or 2.0 V ^e	Temp ^a	Limits - 40 to 85 °C			Unit		
				Min ^b	Typ ^c	Max ^b			
Analog Switch									
Analog Signal Range ^d	V _{NO} , V _{NC} , V _{COM}		Full	0		V+	V		
On-Resistance ^d	r _{ON}	V+ = 4.2 V I _{NO} , I _{NC} = 10 mA	Room Full		2.2	2.9 3.1	Ω		
r _{ON} Flatness ^d	r _{ON} Flatness		V _{COM} = 1, 2, 3.5 V	Room		0.53		1.0	
On-Resistance Match Between Channels ^d	Δr _{DS(on)}		V _{COM} = 3.5 V	Room				0.25	
Switch Off Leakage Current	I _{NO(off)} I _{NC(off)}	V+ = 5.5 V, V _{NO} , V _{NC} = 1 V/4.5 V, V _{COM} = 4.5 V/1 V	Room Full	- 2 - 20		2 20	nA		
	I _{COM(off)}		Room Full	- 2 - 20		2 20			
Channel-On Leakage Current	I _{COM(on)}	V+ = 5.5 V, V _{NO} , V _{NC} = V _{COM} = 1 V/4.5 V	Room Full	- 2 - 20		2 20			
Digital Control									
Input High Voltage ^d	V _{INH}		Full	2.0			V		
Input Low Voltage	V _{INL}		Full			0.8			
Input Capacitance	C _{in}		Full		5		pF		
Input Current	I _{INL} or I _{INH}	V _{IN} = 0 or V+	Full	1		1	μA		
Dynamic Characteristics									
Turn-On Time	t _{ON}	V+ = 4.2 V, V _{NO} or V _{NC} = 3.0 V R _L = 300 Ω, C _L = 35 pF	Room Full		15	45 46	ns		
Turn-Off Time	t _{OFF}		Room Full		12	42 43			
Break-Before-Make Time	t _d		Full	1					
Charge Injection ^d	Q _{INJ}	C _L = 1 nF, V _{GEN} = 2.0 V, R _{GEN} = 0 Ω	Room		1		pC		
Off-Isolation ^d	OIRR	R _L = 50 Ω, C _L = 5 pF	Room		- 74		dB		
Crosstalk ^d	X _{TALK}		f = 1 MHz	Room		- 54			
			f = 10 MHz	Room		- 78			
			f = 10 MHz	Room		- 56			
N _O , N _C Off Capacitance ^d	C _{NO(off)}	V _{IN} = 0 or V+, f = 1 MHz	Room		12		pF		
	C _{NC(off)}		Room		12				
Channel-On Capacitance ^d	C _{NO(on)}		Room		40				
	C _{NC(on)}		Room		40				
Power Supply									
Power Supply Current	I+		V _{IN} = 0 or V+	Room Full				1.0 1.0	μA

Notes:

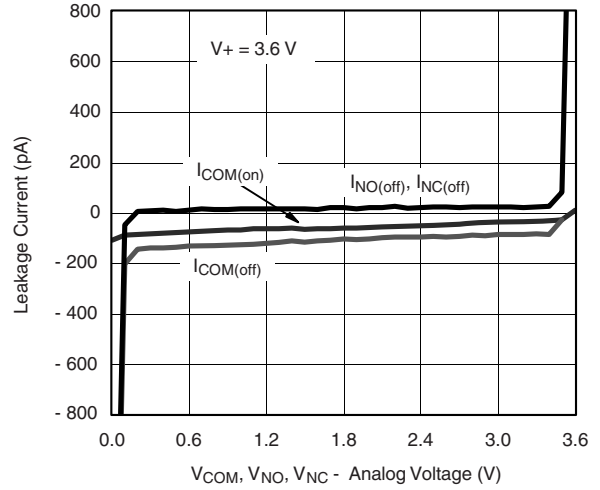
- a. Room = 25 °C, Full = as determined by the operating suffix.
- b. Typical values are for design aid only, not guaranteed nor subject to production testing.
- c. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this data sheet.
- d. Guarantee by design, nor subjected to production test.
- e. V_{IN} = input voltage to perform proper function.
- f. Guaranteed by 5 V testing, not production tested.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted


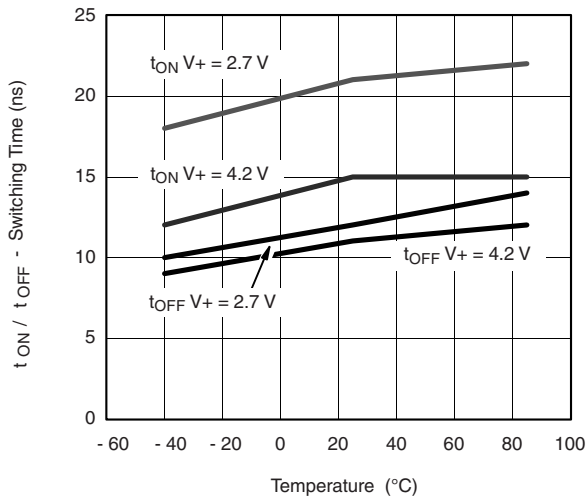
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



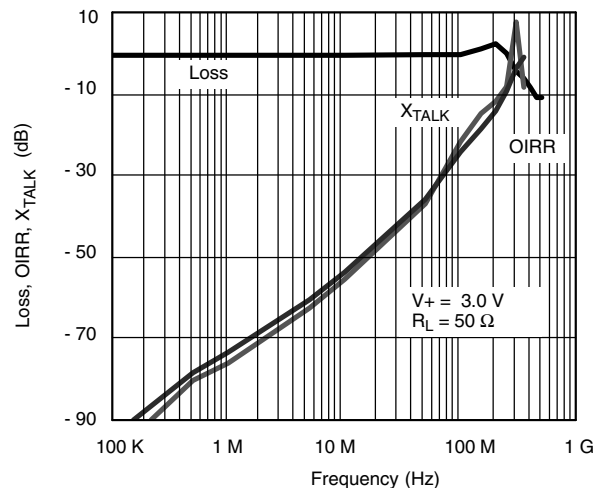
Leakage Current vs. Temperature



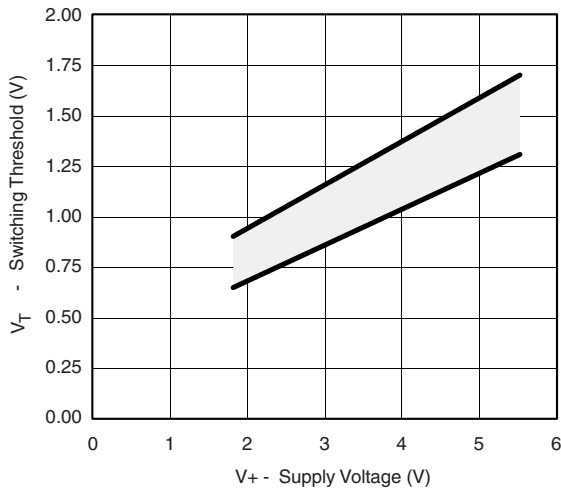
Leakage vs. Analog Voltage



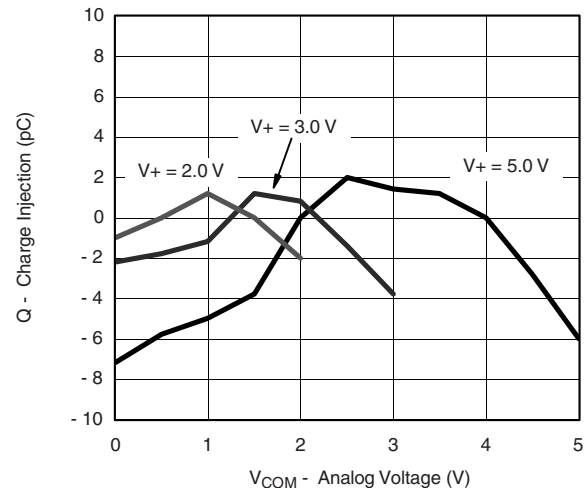
Switching Time vs. Temperature



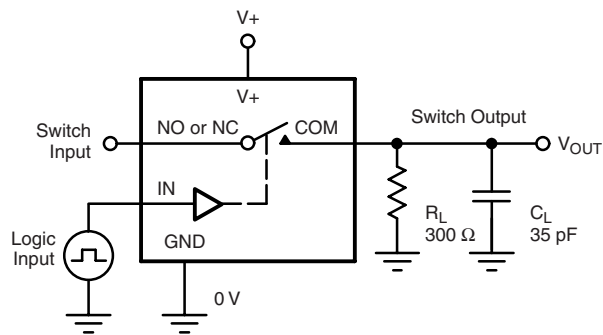
Insertion Loss, Off-Isolation Crosstalk vs. Frequency



Switching Threshold vs. Supply Voltage

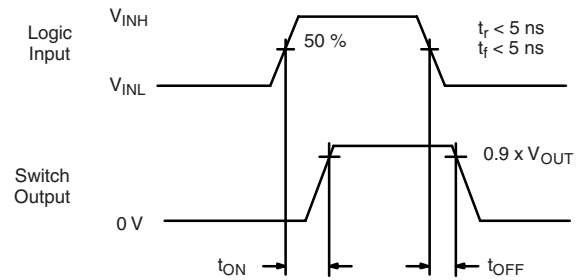


Charge Injection vs. Analog Voltage

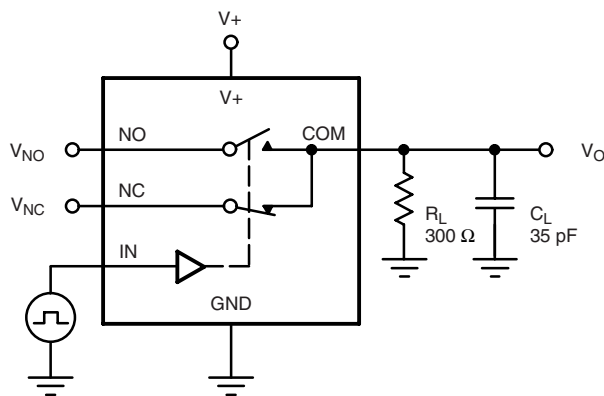
TEST CIRCUITS


C_L (includes fixture and stray capacitance)

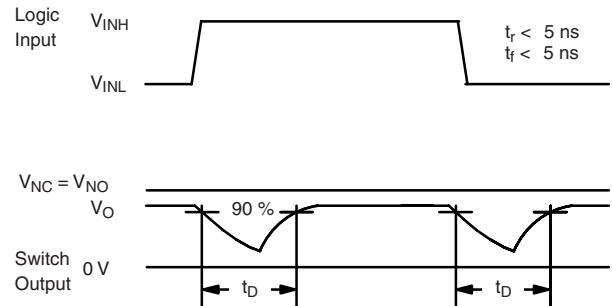
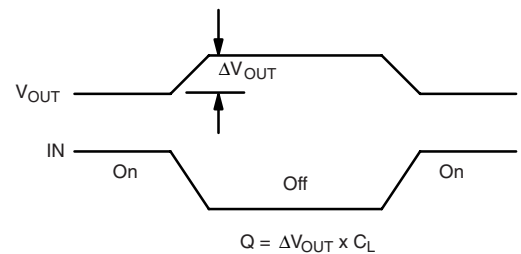
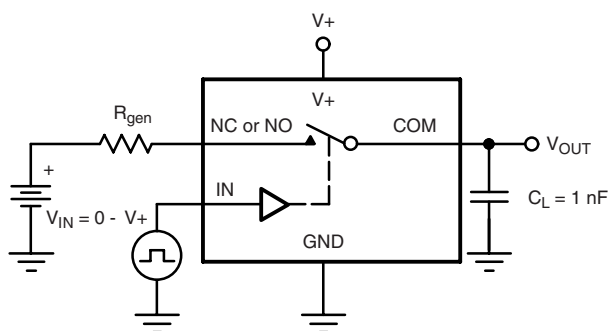
$$V_{OUT} = V_{COM} \left(\frac{R_L}{R_L + R_{ON}} \right)$$



Logic "1" = Switch On
 Logic input waveforms inverted for switches that have the opposite logic sense.

Figure 1. Switching Time


C_L (includes fixture and stray capacitance)


Figure 2. Break-Before-Make Interval


IN depends on switch configuration: input polarity determined by sense of switch.

Figure 3. Charge Injection

TEST CIRCUITS

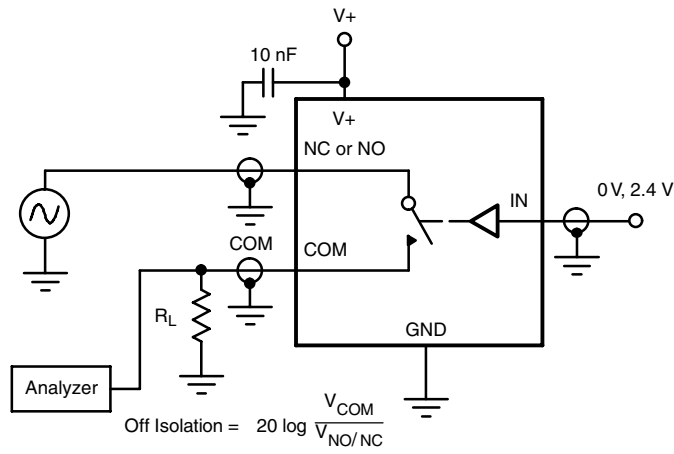


Figure 4. Off-Isolation

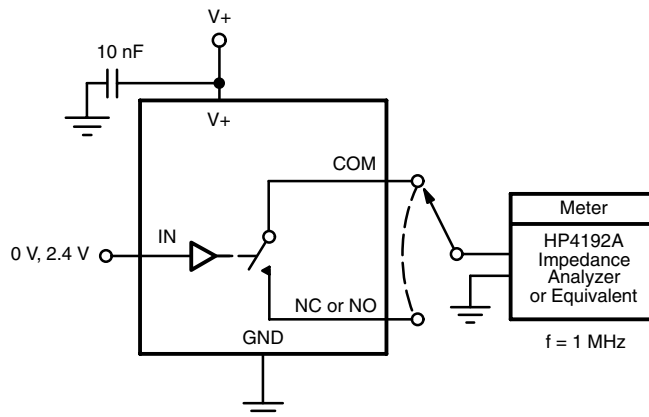
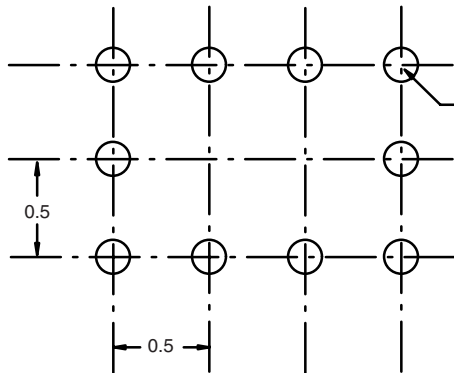
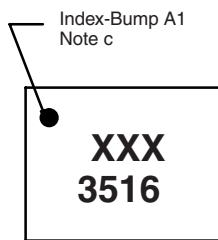


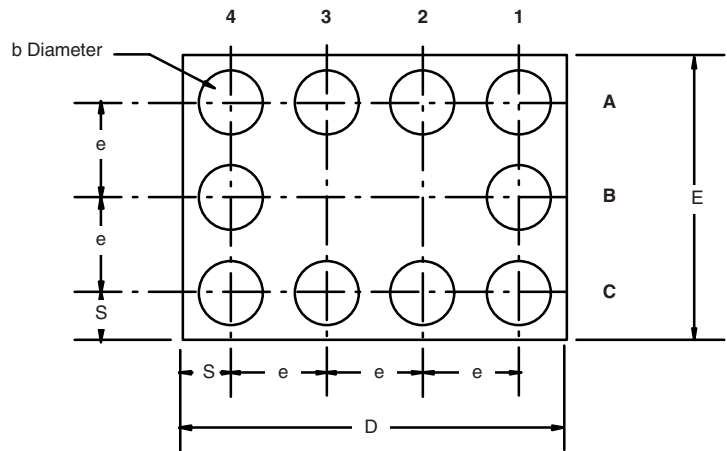
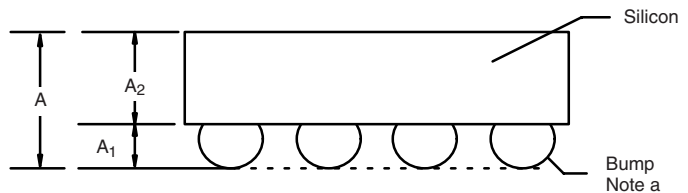
Figure 5. Channel Off/On Capacitance

PACKAGE OUTLINE
MICRO FOOT: 10 BUMP (4 x 3, 0.5 mm PITCH, 0.238 mm BUMP HEIGHT)


Recommended Land Pattern



Top Side (Die Back)



Notes (Unless Otherwise Specified):

- a. Bump is Lead (Pb)-free Sn/Ag/Cu.
- b. Non-solder mask defined copper landing pad.
- c. Laser Mark on silicon die back; back-lapped, no coating. Shown is not actual marking; sample only.

Dim	Millimeters ^a		Inches	
	Min	Max	Min	Max
A	0.688	0.753	0.0271	0.0296
A₁	0.218	0.258	0.0086	0.0102
A₂	0.470	0.495	0.0185	0.0195
b	0.306	0.346	0.0120	0.0136
D	1.980	2.020	0.0780	0.0795
E	1.480	1.520	0.0583	0.0598
e	0.5 BASIC		0.0197 BASIC	
S	0.230	0.270	0.0091	0.0106

Notes:

- a. Use millimeters as the primary measurement.

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